

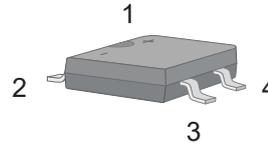


**MB1F-10~MB10F-10**

**Features:**

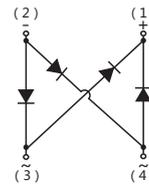
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1.0 A
- High Surge Current Capability
- Designed for Surface Mount Application

**MBF**



CHIP SIZE:50MIL

**PINNING**



| PIN | DESCRIPTION          |
|-----|----------------------|
| 1   | Output Anode ( + )   |
| 2   | Output Cathode ( - ) |
| 3   | Input Pin ( ~ )      |
| 4   | Input Pin ( ~ )      |

**Absolute Maximum Ratings (Ta=25°C unless otherwise noted)**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Parameter   | Symbols                            | MB1F-10    | MB2F-10 | MB4F-10 | MB6F-10 | MB8F-10 | MB10F-10 | Units        |
|---|------------------------------------|------------|---------|---------|---------|---------|----------|--------------|
| Maximum Repetitive Peak Reverse Voltage   | $V_{RRM}$                          | 100        | 200     | 400     | 600     | 800     | 1000     | V            |
| Maximum RMS voltage   | $V_{RMS}$                          | 70         | 140     | 280     | 420     | 560     | 700      | V            |
| Maximum DC Blocking Voltage   | $V_{DC}$                           | 100        | 200     | 400     | 600     | 800     | 1000     | V            |
| Average Rectified Output Current at $T_c = 125^\circ C$   | $I_o$                              | 1.0        |         |         |         |         |          | A            |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | $I_{FSM}$                          | 35         |         |         |         |         |          | A            |
| Maximum Forward Voltage at 1.0 A  | $V_F$                              | 1.1        |         |         |         |         |          | V            |
| Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A=25^\circ C$<br>@ $T_A=125^\circ C$ | $I_R$                              | 5<br>40    |         |         |         |         |          | $\mu A$      |
| Typical Junction Capacitance ( Note1 )  | $C_j$                              | 13         |         |         |         |         |          | pF           |
| Typical Thermal Resistance ( Note2 )  | $R_{\theta JA}$<br>$R_{\theta JC}$ | 80<br>25   |         |         |         |         |          | $^\circ C/W$ |
| Operating and Storage Temperature Range   | $T_j, T_{stg}$                     | -55 ~ +150 |         |         |         |         |          | $^\circ C$   |

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.  
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

Typical Characteristics

Fig.1 Average Rectified Output Current Derating Curve

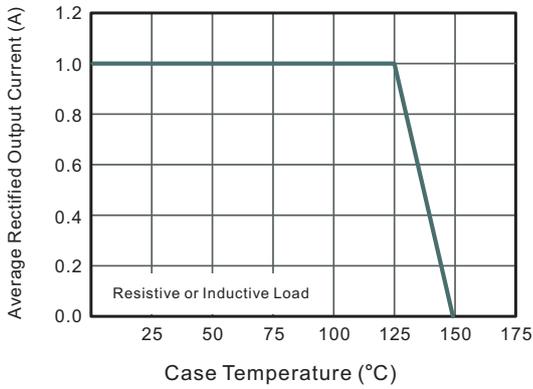


Fig.2 Typical Reverse Characteristics

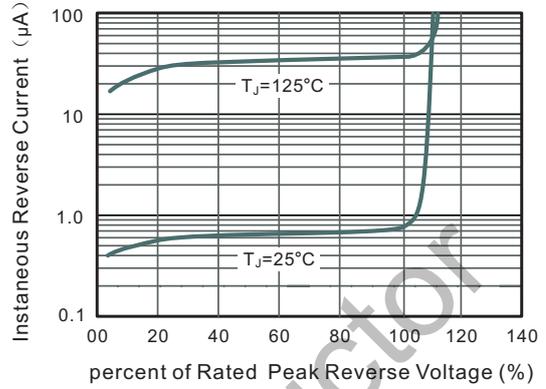


Fig.3 Typical Instantaneous Forward Characteristics

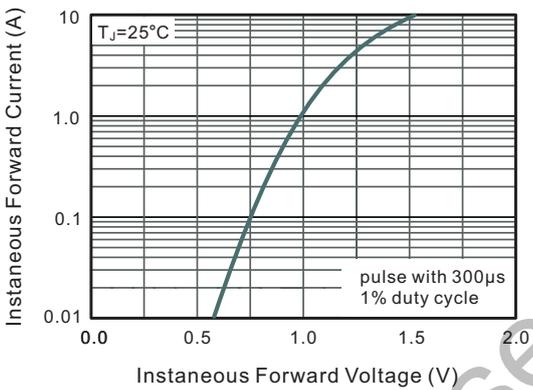


Fig.4 Typical Junction Capacitance

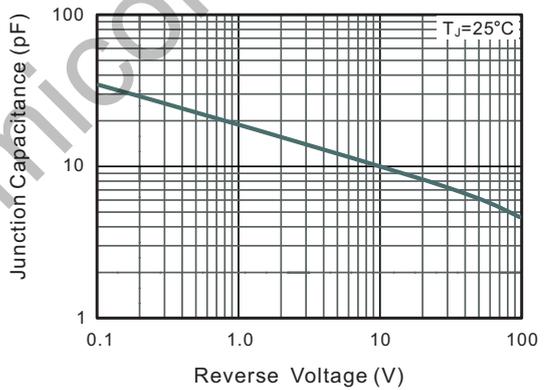
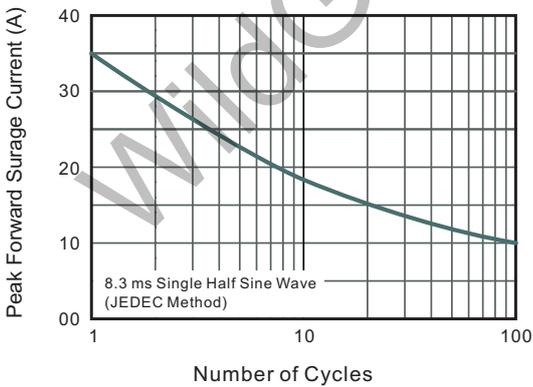
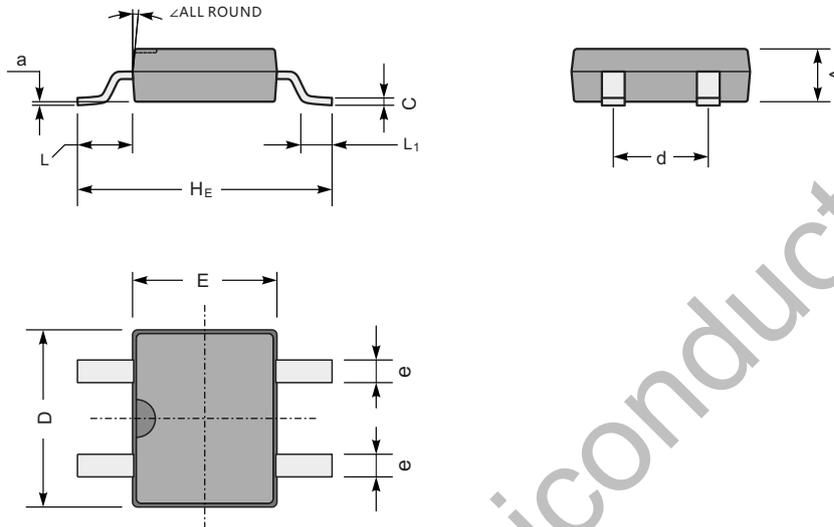


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



**Package Dimension**

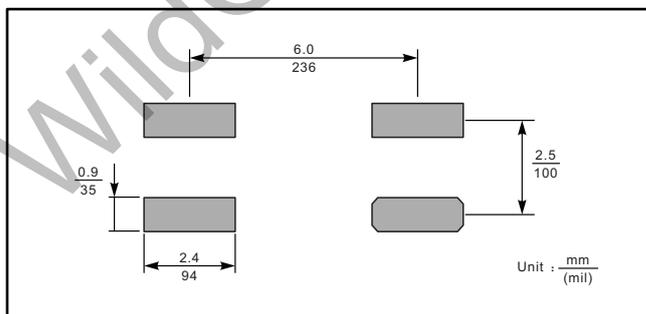
**MBF**



MBF mechanical data

| UNIT |     | A   | C    | D   | E   | HE  | d   | e   | L   | L1  | a   | ∠  |
|------|-----|-----|------|-----|-----|-----|-----|-----|-----|-----|-----|----|
| mm   | max | 1.6 | 0.22 | 5.0 | 4.1 | 7.0 | 2.7 | 0.8 | 1.7 | 1.1 | 0.2 | 7° |
|      | min | 1.2 | 0.15 | 4.5 | 3.6 | 6.4 | 2.3 | 0.5 | 1.3 | 0.5 | —   |    |
| mil  | max | 63  | 8.7  | 197 | 161 | 276 | 106 | 31  | 67  | 43  | 8   |    |
|      | min | 47  | 5.9  | 177 | 142 | 252 | 91  | 20  | 51  | 20  | —   |    |

**The recommended mounting pad size**



**Marking**

| Type number | Marking code |
|-------------|--------------|
| MB1F-10     | MB1F         |
| MB2F-10     | MB2F         |
| MB4F-10     | MB4F         |
| MB6F-10     | MB6F         |
| MB8F-10     | MB8F         |
| MB10F-10    | MB10F        |